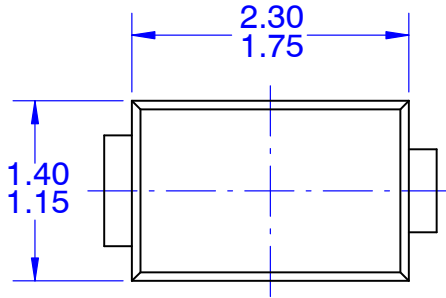


MECHANICAL CASE OUTLINE
PACKAGE DIMENSIONS

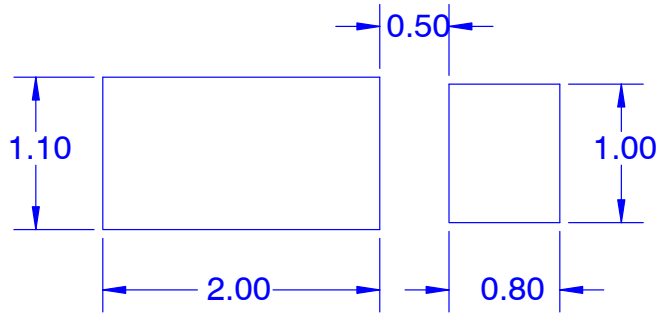


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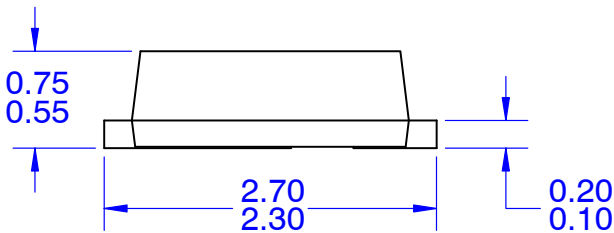
DATE 31 AUG 2016



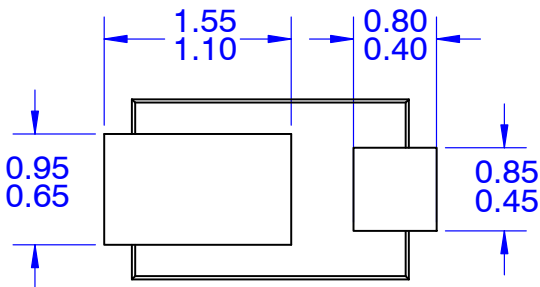
TOP VIEW



LAND PATTERN RECOMMENDATION



FRONT VIEW



BOTTOM VIEW

NOTES:

- A. THIS PACKAGE DOES NOT CONFORM TO ANY STANDARDS.
- B. ALL DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.

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